Electronic Supplementary Material (ESI) for Analyst.

Chemically robust succinimide group-assisted irreversible bonding of poly(dimethylsiloxane)–thermoplastic microfluidic devices at room temperature

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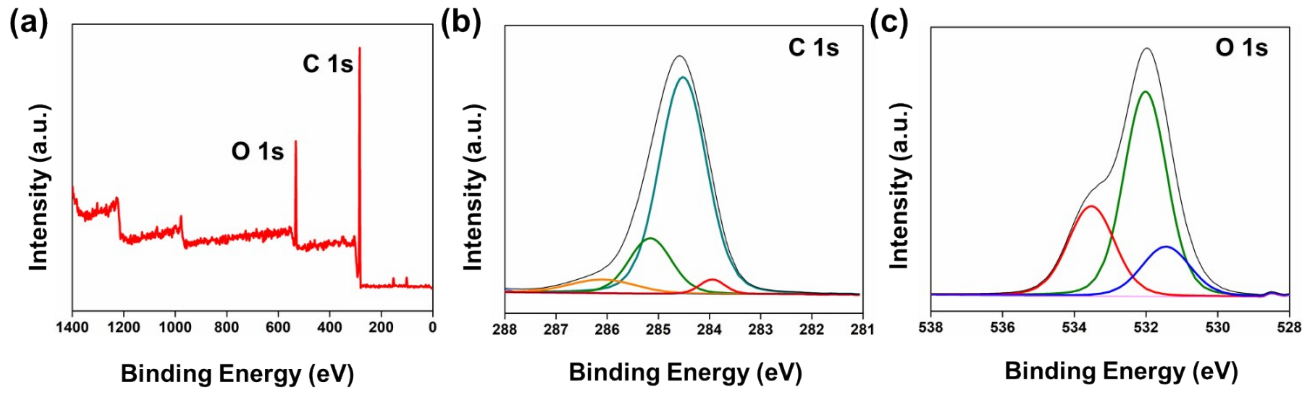

Fig S1. High resolution XPS spectra for PC. (a) survey spectrum, (b) C1s, and (c) O1s.

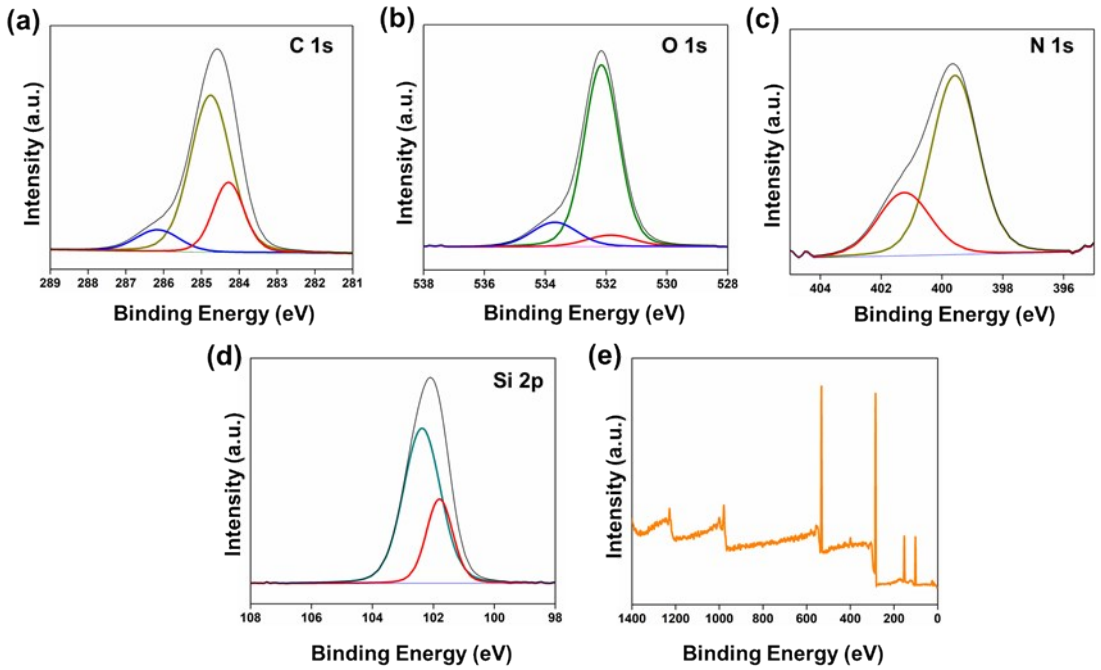

Fig S2. High resolution XPS spectra for APTES-coated PC. (a) C1s, (b) O1s, (c) N1s (d) Si2p and (e) survey spectrum.

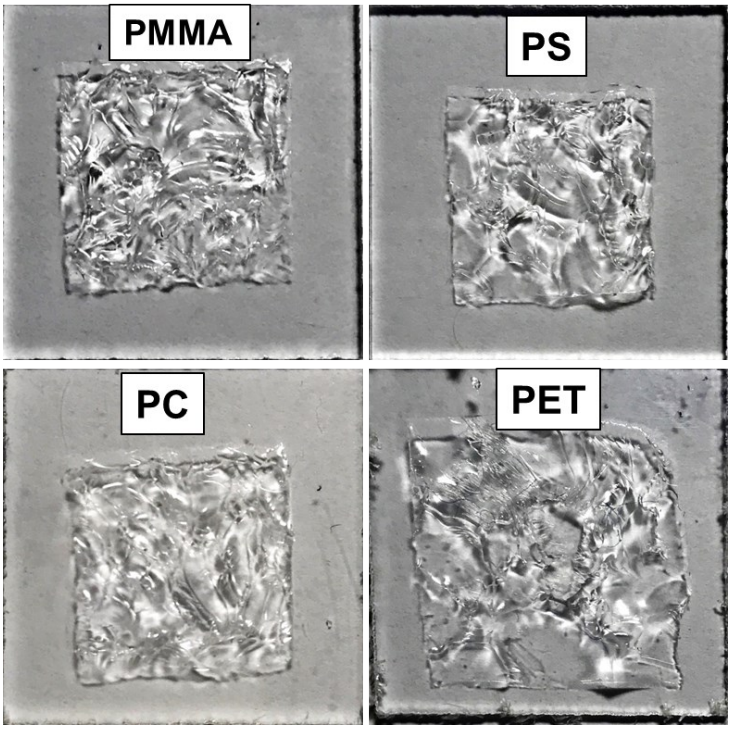

Fig S3. Results of delamination test when various substrates (PMMA, PS, PC, and PET) were used for bonding with PDMS.

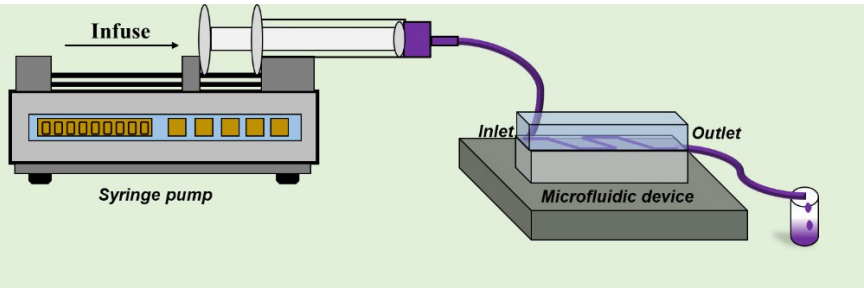

Fig S4. Schematic illustration of leakage test.

Table S1

Atomic ratio of pristine PDMS and TESPSA coated PDMS

Substrate	Spectrum	Atomic ratio (%)
Pristine PDMS	O1s	42.9
	C1s	40.1
	Si2p	**16.8**
TESPSA coated PDMS	O1s	41.0
	C1s	41.1
	Si2p	**17.8**